

Inventor: Fernando Gonzalez
Title: Methods of Forming Semiconductor Constructions
Assignee: Micron Technology, Inc.

INFORMATION DISCLOSURE STATEMENT

PURSUANT TO 37 C.F.R. §§ 1.56, 1.97 AND 1.98

In compliance with 37 C.F.R. §§ 1.56, 1.97 and 1.98, your attention is directed to the United States patents and other references listed on the attached Form PTO-1449. No admission is made regarding whether all the submitted references are prior art.

The listed references were cited by, or submitted to, the Office in the parent, co-pending application of the above-identified application. The above-identified application is a continuation application of co-pending application Serial No. 10/271,888, filed October 15, 2002. Such prior disclosure is sufficient for the above-identified application as far as copies of the references are concerned. 37 C.F.R. § 1.98(d) and MPEP § 609(2).

Citation of these references is respectfully requested.

Dated: _____

8/19/03

By: _____

Respectfully submitted,

David G. Latwesen, Ph.D.
Reg. No. 38,533

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-2383	Priority SERIAL NO. 10/271.888	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT Fernando Gonzalez		
				Priority FILING DATE October 15, 2002	Priority GROUP 2818	
U.S. PATENT DOCUMENTS						
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	AA	6,309,945 B1	10/01	Sato et al.		
	AB	5,298,449	03/94	Kikuchi		
	AC	5,374,564	12/94	Bruehl		
	AD	5,855,693	01/99	Murari et al.		
	AE	5,877,070	03/99	Goesele et al.		
	AF	5,882,987	03/99	Srikrishnan		
	AG	5,894,152	04/99	Jaso et al.		
	AH	5,953,622	09/99	Lee et al.		
	AI	6,004,406	12/99	Kobayashi et al.		
	AJ	6,251,754	6/01	Ohshima et al.		
	AK	6,245,161	6/01	Henley et al.		
	AL	5,374,581	12/94	Ichikawa et al.		
	AM	4,891,329	1/90	Reisman et al.		
	AN	6,150,031	11/00	Yonehara		
	AO	6,083,324	7/00	Henley et al.		
	AP	6,309,945	10-2001	Sato et al.		
	AQ	6,423,992 B2	07/02	Fukuda et al.		
	AR	6,384,439 B1	05/02	Walker		
	AS	5,998,847	12/99	Assaderaghi et al.		
FOREIGN PATENT DOCUMENTS						
	Document Number	Date	Country	Class	Subclass	Translation Yes No
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)						
AT	Gösele, U. et al., "Semiconductor Wafer Bonding: Science, Technology, and Applications", Electrochemical Society Proceedings					
	Vol. 97-36, (©1998), pp. 400-425, 436-445.					
EXAMINER			DATE CONSIDERED			
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>						